



Atty. Dkt. No. 039262-0156

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Tadahiro OHMI et al
Title: METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE
AND METHOD OF ETCHING AN INSULATING FILM
Appl. No.: 10/588,698
International Filing Date: 2/2/2005
371(c) Date: 8/8/06
Examiner: Caridad Everhart
Art Unit: 2891
Confirmation Number: 9929

AMENDMENT AND REPLY UNDER 37 CFR 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This communication is responsive to the Non-Final Office Action dated April 10, 2008, concerning the above-referenced patent application. Applicants have paid with this amendment a three-month extension of time to make this response timely.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this document.

Remarks/Arguments begin on page 7 of this document.

Please amend the application as follows:

10/09/2008 JADDU1 00000027 190741 10588698
01 FC:2253 30.00 DA 525.00 OP